

UTILITY PATENT APPLICATION

HONORABLE COMMISSIONER OF
PATENTS AND TRADEMARKS
Washington D.C. 20231

Docket No.: 3008-28
Client Ref.: PHNF-01094

1046 U.S. PTO
09/892630
06/28/01

TO/82/90

Sir:

Transmitted herewith for filing is the patent application of:

INVENTOR(S): Seigi Aoyama, Takaaki Ichikawa, Hiromitsu Kuroda, Takashi Nemoto, Atsushi Otake and Hiroyoshi Hiruta
FOR: LEAD FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL COMPONENT USING SAID LEAD FREE SOLDER

Enclosed are:

- 24 pages of specification, claims, abstract
- Declaration & Power of Attorney.
- Priority Claimed
- 4 sheets of drawing.
- An assignment of the invention to Hitachi Cable Ltd. and the assignment recordation fee.
- Certified copy of JP Application No. 2001-61650
- An associate power of attorney.
- Preliminary Amendment
- Information Disclosure Statement, Form PTO-1449 and reference.

The filing fee has been calculated as shown below:

(1) FOR	(2) NO. FILED	(3) NO. EXTRA	(4) RATE	(5) AMOUNT	
TOTAL CLAIMS	13	-20	0	x \$18.00 =	\$.00
INDEPENDENT CLAIMS	3	-3	0	x \$80.00 =	.00

MULTIPLE DEPENDENT

CLAIM(S) (If applicable) + \$ ____ .00 = 00.00

BASIC FEE \$710.00

Total of above calculations = \$710.00

Subtract $\frac{1}{2}$ if Small Entity = \$ ____ .00

Assignment & Recording Fee \$40.00

TOTAL FEE \$750.00